

A Division of

Product Change Notification

PCN No: PCN2023-0001

Date: Jan. 6th, 2023

Change Notification: Adding Assembly & FT house and changing bonding wires to copper

To: Valued Customers

From: ISSI (Integrated Silicon Solution, Inc.)

1623 Buckeye Dr. Milpitas, CA. 95035 USA

Affected Product:

IS31FL3726A-ZLS4-TR

Description of Change:

Lumissil Microsystems is adding an Assembly and Final Test facility – TFME (Nantong Fujitsu Microelectronics Company., LTD) for the product IS31FL3726A-ZLS4-TR. TFME is located in Nan-tong, Jiang-su, China. Current assembly and final test house is Greatek in Tai-wan. In addition, the product bonding wires will be changed from Gold to copper. there is no change in fit or function. Reliability qualification has been completed.

Rationale for Change:

Improving back end PKG support capability for customer's future needs

Schedule:

Samples are Available for Evaluation: please contact your local Lumissil Sales.

Qualification Data report: Available Upon Request.

Mass Production Date: May 1st ,2023

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